

**Product / Package Information**

Package	SOT143
Body Size	
Lead Count	4
Terminal Finish	100 Sn

**Environmental Compliance Information**

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	5.00 E-03	83.25	832500	48.52	485168
Thermosets	Epoxy resin	Proprietary	3.25 E-04	5.42	54200	3.16	31587
Thermosets	Phenol resin	Proprietary	2.07 E-04	3.45	34500	2.01	20106
Other inorganic materials	Metal Hydroxide	Proprietary	3.25 E-04	5.42	54200	3.16	31587
Others	Others	Proprietary	1.48 E-04	2.46	24600	1.43	14336
Subtotal			6.00 E-03	100.0	1000000	58.28	582784

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Iron & its alloys	Iron	7439-89-6	1.82 E-03	56.70	567000	17.72	177198
Iron & its alloys	Nickel	7440-02-0	1.34 E-03	41.50	415000	12.97	129695
Iron & its alloys	Manganese	7439-96-5	2.57 E-05	0.80	8000	0.25	2500
Iron & its alloys	Cobalt	7440-48-4	1.61 E-05	0.50	5000	0.16	1563
Iron & its alloys	Silicon	7440-21-3	9.65 E-06	0.30	3000	0.09	938
Iron & its alloys	Chromium	7440-47-3	3.22 E-06	0.10	1000	0.03	313
Iron & its alloys	Aluminum	7429-90-5	3.22 E-06	0.10	1000	0.03	313
Subtotal			3.22 E-03	100.00	1000000	31.25	312518

**Internal Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.25 E-05	100.0	1000000	0.32	3157

**External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	3.85 E-04	100.0	1000000	3.74	37435

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.00 E-04	99.99	1000000	0.97	9713

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	5.00 E-04	100.0	1000000	4.86	48565

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silicon Dioxide	Proprietary	2.76 E-05	46.00	460000	0.27	2681
Thermoset	Epoxy Resin	Proprietary	2.76 E-05	46.00	460000	0.27	2681
Others	Curing agent & hardener	Proprietary	4.80 E-06	8.00	80000	0.05	466
Subtotal			6.00 E-05	100	1000000	0.58	5828

<b>Package Totals</b>			<b>Weight (g)</b>	<b>1.03 E-02</b>		<b>Percentage (%)</b>	<b>100.00</b>	<b>PPM</b>	<b>1000000</b>
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Note: The information provided in this declaration are true to the best of ADI's knowledge  
 ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability  
 any inaccuracy of such information.



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